

Features

- Compact high-efficiency 1-cell switching charger
 - Proprietary sensorless charge current control
 - 4.1V to 6.2V input voltage with 28V absolute maximum input voltage rating
 - Charge voltages: 4.20V / 4.35V
 - 2.0A continuous fast charge current
 - 1.2MHz switching frequency
 - 93.5% high efficiency @ VBAT=4V, ICHG=1A
 - 89% high efficiency @ VBAT=4V, ICHG=2A
 - Input voltage regulation to allow weak input power source to charge battery (VINDPM)
 - Support trickle charge, precharge, Constant Current (CC) charge, Constant Voltage (CV) charge, charge termination and recharge
- High charge accuracy
 - +/- 0.5% charge voltage regulation
 - +/- 10% charge current regulation
- High integration
 - Integrated all MOSFETs
 - Internal loop compensation
 - LED charge indication driver
- Protections
 - Cycle-by-cycle current limit protection
 - Input over-voltage protection (OVP)
 - Cold/hot battery temperature monitoring
 - Junction temperature thermal regulation (TREG)
 - ISET pin short and open protection
- Packaging
 - DFN2x2-8L
 - RoHS compliant and halogen free
 - 100% lead (Pb) free

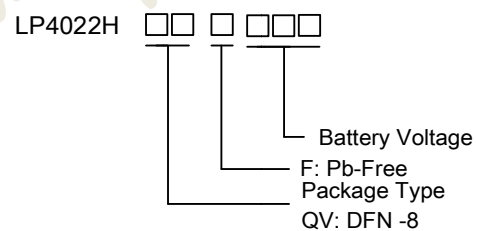
Applications

- IoT devices
- Wearable devices
- Gaming devices
- Portable electronics
- E-Cigarette

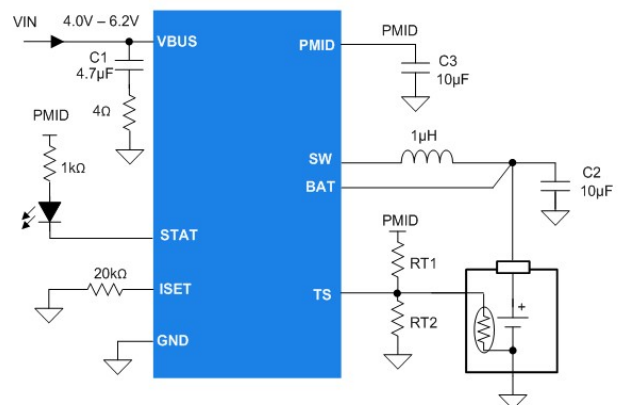
General Description

The LP4022H is a standalone 1-cell switching battery charger that delivers up to 2A of charge current from a 4.1V to 6.2V input voltage. The charge current is programmable via a resistor connected between the ISET pin and GND. Charging can be enabled or disabled through the ISET pin or TS pin. Operating at a 1.2MHz switching frequency, the LP4022H supports the use of a compact 2.0 × 1.6 mm, 1-μH inductor for fast 2A charging. LPS's patented integrated current sensing and control technology eliminates the need for an external sensing resistor, enabling high charge efficiency, low BOM cost, and a small form factor. The LP4022H is offered in a DFN2x2-8L package, providing one of the most compact switching charging solutions available on the market, ideal for space-constrained systems.

Order Information



Application Circuit

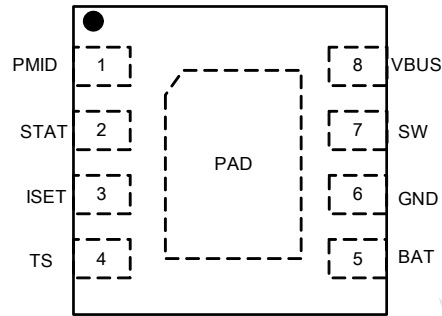


Device Information

Part Number	Battery Voltages	Top Marking	Package	Moisture Sensitivity Level	Shipping
LP4022HQVF	4.2V	LPS BpYWX	DFN2x2-8	MSL3	4K/REEL
LP4022HQVF-435	4.35V	LPS BQYWX	DFN2x2-8	MSL3	4K/REEL

Marking indication: Y: Year code. W: Week code. X: Batch numbers.
MSL: Moisture Sensitivity Level according to JEDEC Standard

Pin Diagram



DFN 2x2 – 8L
(Top View)

Pin Description

Pin Name	Pin Number	Description
PMID	1	Output of the source of over voltage protection N-channel MOSFET (OVPFET) and the source of high-side P-channel MOSFET (HSFET). Place ceramic 10 μ F on PMID to GND and place it as close as possible to IC. PMID voltage is clamped once VBUS over voltage is detected.
STAT	2	Charge status indication output. Connect a LED from PMID pin to STAT pin via a current limiting resistor. The STAT pin indicates charger status: Charge in progress: STAT pin is pulled LOW Charge complete or charger in SLEEP mode: STAT pin is OPEN
ISET	3	Charge current program input. Connect a 1% resistor RISET from this pin to ground to program the charge current. If ISET pin is floating, charge current is minimized. If ISET pin is pulled higher than 1V or below 0.35V, charge is disabled. ISET can be used to enable and disable charge.
TS	4	Battery temperature sense thermistor input. Charge is suspended if the battery thermistor temperature is out of range. Leave the TS pin floating if TS pin function is not used.
BAT	5	Battery connection pin. Connect this pin to node of inductor output terminal and battery pack positive terminal. $\geq 10\mu$ F capacitor is recommended to connect to this node.
GND	6	Power ground and analog ground.
SW	7	Switching node. Internally SW node is connected to the source of the P-channel HSFET and the drain of the N-channel LSFET. Connect this pin to a terminal of external inductor.
VBUS	8	Charger input connection. The internal over voltage protection N-channel MOSFET (OVPFET) is connected between VBUS and PMID with VBUS on drain. Place a 4.7 μ F or higher ceramic capacitor from VBUS to GND and place it as close as possible to the device.
PAD	9	Thermal pad. Connected to GND on top layer and connected to ground plane by multiple vias for heat dissipation.

Absolute Maximum Ratings ⁽¹⁾

VBUS voltage to GND-----	-0.3V to 28V
PMID, SW Voltage to GND -----	-0.3V to 7V
BAT Voltage to GND -----	-0.3V to 6V ⁽²⁾
STAT, ISET, TS Voltages to GND -----	-0.3V to 6V
STAT Sink Current-----	6mA
Maximum Junction Temperature (T _j)-----	150°C
Storage Temperature Range -----	-40°C to 150°C
Maximum Soldering Temperature (at leads, 10 sec)-----	260°C

Note1: Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note 2: Surge protection is internally built in at BAT pin to stand voltage surge at this pin.

ESD Ratings

HBM (Human Body Model) -----	2kV
MM (Machine Model)-----	200V
CDM (Charge Discharge Model) -----	500V

Thermal Information

θ _{JA} (Junction-to-Ambient Thermal Resistance) -----	50°C/W
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Recommended Operating Conditions

SYMBOL	PARAMETER	MIN	TYP	MAX	UNIT
V _{IN}	Input Voltage	4.1		6.2	V
I _{CHG}	Fast Charge Current	0.35		2.0	A
V _{BAT}	Battery Charge Voltage		4.2 / 4.35		V
T _J	Operating Junction Temperature Range (T _J)	-40		125	°C
T _A	Ambient Temperature Range	-40		85	°C
L	Output Inductance	0.7	1	2.64	μH
C _{IN}	Input Capacitance at VBUS	1.4	4.7		μF
C _{PMID}	PMID Capacitance	3	10		μF
C _{BAT}	BAT Capacitance	3	10		μF

Notes:

- (1) The values recommended in the table are effective inductance and capacitance.

(2)

Electrical Characteristics

(The (The specifications are at $V_{VBUS_LOWV} < V_{VBUS} < V_{VBUS_OVP}$ and $V_{VBUS} > V_{BAT} + V_{SLEEP}$, $L=1\mu H$, $T_J = 25^\circ C$ unless otherwise noted)

SYMBOL	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
QUIESCENT CURRENT						
I_{Q_BAT}	Battery reverse current	$V_{BAT} = V_{SW} = 4.35V$, VBUS pin is floating			1	μA
I_{Q_BAT}	Battery leak current	Charge is terminated, $V_{BAT}=4.35V$			5	μA
I_{Q_BAT}	Battery leak current	ISET pin short to GND, $V_{BAT}=4.35V$			5	μA
OVER VOLTAGE PROTECTION						
$V_{VBUS_OVP_RISE}$	VBUS input overvoltage threshold	V_{VBUS} rising	6.2	6.4	6.6	V
$V_{VBUS_OVP_HYS}$	VBUS input overvoltage threshold hysteresis	V_{VBUS} falling		0.5		V
V_{PMID_CLAMP}	PMID voltage	PMID voltage at $V_{VBUS}=12V$		5		V
MOSFETS						
R_{DSON_Q1}	OVPFET on-resistance	$V_{VBUS}=5V$		75		m Ω
R_{DSON_Q2}	HSFET on-resistance	$V_{VBUS}=5V$		80		m Ω
R_{DSON_Q3}	LSFET on-resistance	$V_{VBUS}=5V$		180		m Ω
INPUT VOLTAGE						
V_{VBUS}	VBUS operation range		4.1		6.2	V
V_{UVLO_RISE}	Under voltage lock out(UVLO) voltage	V_{VBUS} rising	3.65	3.75	3.85	V
V_{UVLO_FALL}	UVLO voltage	V_{VBUS} falling		300		mV
V_{SLEEP}	Into sleep mode threshold	V_{VBUS} falling, $V_{BAT} - V_{VBUS}$	30	60	90	mV
V_{SLEEPZ}	Exit sleep mode threshold	V_{VBUS} rising, $V_{VBUS}-V_{BAT}$	140	180	230	mV
V_{INDPM_MIN}	Minimum VINDPM at VBUS	$V_{BAT}=3.5V$ Regulated at VBUS pin	3.9	4.0	4.1	V
ISET Pin						
V_{ISET}	ISET pin voltage		0.985	1	1.015	V
K_{ICHG}	Charge current ratio	$R_{ISET} = 23.2k\Omega, 40.2k\Omega$ $ICHG=K_{ICHG}/R_{ISET}$	10%	40	10%	Axk Ω
K_{ICHG}	Charge current ratio	$R_{ISET} = 78.7k\Omega$ $ICHG=K_{ICHG}/R_{ISET}$	15%	40	15%	Axk Ω
V_{ISET_LOW}	ISET voltage low			0.35		V

Electrical Characteristics

(The specifications are at $V_{VBUS_LOWV} < V_{VBUS} < V_{VBUS_OVP}$ and $V_{VBUS} > V_{BAT} + V_{SLEEP}$, $L=1\mu H$, $T_J = 25^\circ C$ unless otherwise noted)

SYMBOL	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
BATTERY CHARGER						
V_{BATREG}	Charge voltage	CV regulation voltage at BAT pin	4.179	4.2	4.221	V
			4.328	4.35	4.372	V
I_{CHG}	Fast charge current	$I_{CHG}=2A, V_{VBUS}=5V, V_{BAT}=3.8V$ $R_{ISET}=20k\Omega$	1800	2000	2200	mA
I_{CHG}	Fast charge current	$I_{CHG}=1A, V_{VBUS}=5V, V_{BAT}=3.8V$ $R_{ISET}=40k\Omega$	900	1000	1100	mA
I_{PRECHG}	Precharge current	$I_{CHG}=2A, V_{VBUS}=5V, V_{BAT}=2.5V$ $R_{ISET}=20k\Omega$	140	200	260	mA
I_{PRECHG}	Precharge current	$I_{CHG}=1A, V_{VBUS}=5V, V_{BAT}=2.5V$ $R_{ISET}=40k\Omega$	50	100	150	mA
I_{BAT_SHORT}	Trickle charge current	$V_{VBUS}=5V, V_{BAT}=1.0V$	45	60	75	mA
I_{TERM}	Termination current	$I_{CHG}=2A, V_{BATREG}=4.2V$ $R_{ISET}=20k\Omega$	140	200	260	mA
I_{TERM}	Termination current	$I_{CHG}=1A, V_{BATREG}=4.2V$ $R_{ISET}=40k\Omega$	50	100	150	mA
$V_{BAT_SHORT_RISE}$	V_{BAT} short rising threshold	From battery short to precharge	1.85	2.00	2.15	V
$V_{BAT_SHORT_FALL}$	V_{BAT} short falling threshold	From precharge to battery short	1.65	1.80	1.95	V
$V_{BAT_LOWV_RISE}$	V_{BAT} fast charge rising threshold	Precharge to fast charge	2.9	3.0	3.1	V
$V_{BAT_LOWV_FALL}$	V_{BAT} fast charge falling threshold	Fast charge to precharge charge	2.6	2.7	2.8	V
V_{RECHG_HYS}	Recharge threshold	V_{BAT} falling	120	150	180	mV
STAT						
I_{STAT_PD}	STAT pull-down current				6	mA

Electrical Characteristics

(The specifications are at $V_{VBUS_LOWV} < V_{VBUS} < V_{VBUS_OVP}$ and $V_{VBUS} > V_{BAT} + V_{SLEEP}$, $L=1\mu H$, $T_J = 25^\circ C$ unless otherwise noted)

SYMBOL	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
SWITCHING CONVERTER						
F_{SW}	Switching Frequency			1210		kHz
I_{HSFET_OCP}	HSFET Over Current Protection			3.3		A
D_{MAX}	Maximum duty cycle				100	%
COLD/HOT THERMISTOR COMPARATOR						
$V_{T1}\%$	T_{COLD} (0°C) threshold, charge suspend if V_{TS} is above the threshold	V_{TS} rising, as percentage of V_{PMID}	73	73.5	74	%
$V_{T1}\%$		V_{TS} falling, as percentage of V_{PMID}		71.5		%
$V_{T3}\%$	T_{HOT} (45°C) threshold, charge suspend if V_{TS} is below the threshold	V_{TS} falling, as percentage of V_{PMID}	47	47.25	47.5	%
$V_{T3}\%$		V_{TS} rising, as percentage of V_{PMID}		48.25		%
THERMAL REGULATION AND THERMAL SHUTDOWN						
T_{REG}	Thermal regulation			130		°C
T_{SHUT_RISE}	Thermal shut down	Temperature rise		150		°C
T_{SHUT_FALL}	Thermal shut down	Temperature fall		120		°C

Typical Characteristics

(L=1μH, CPMID=10μF, CIN= 2.2μF and T_J = 25°C unless otherwise noted)

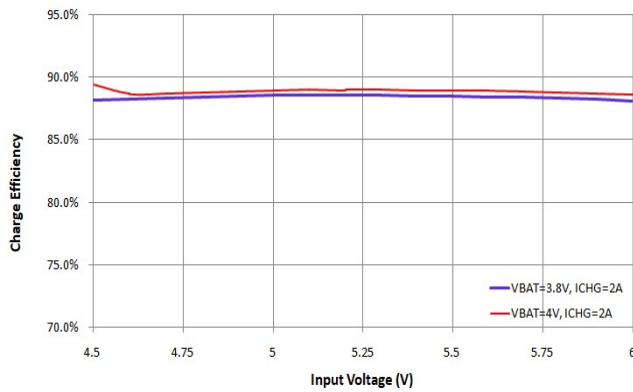


Figure 1. Charge Efficiency vs. Vin

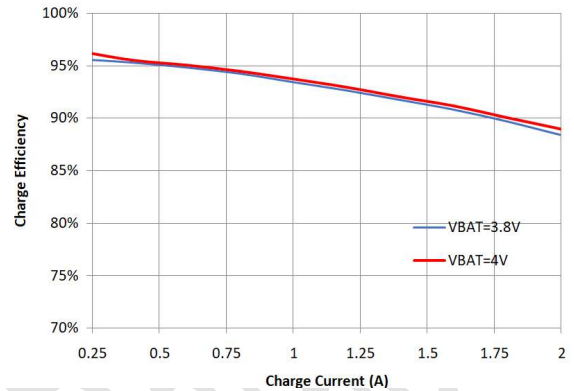


Figure 2. Charge Efficiency vs. Charge Current (V_{IN}=5V)

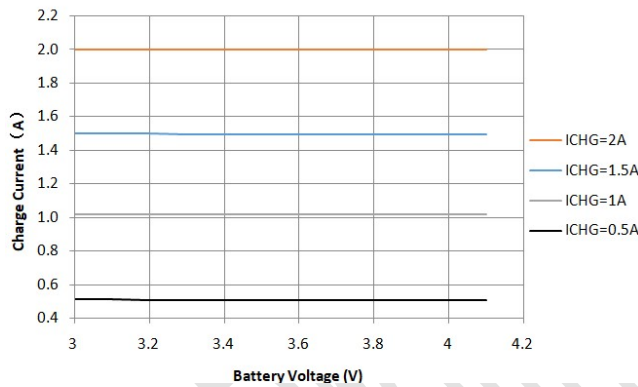


Figure 3. Charge Current vs. Battery Voltage

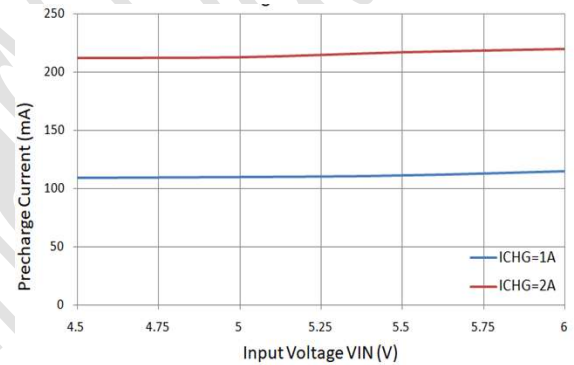


Figure 4. Precharge current vs. Input Voltage

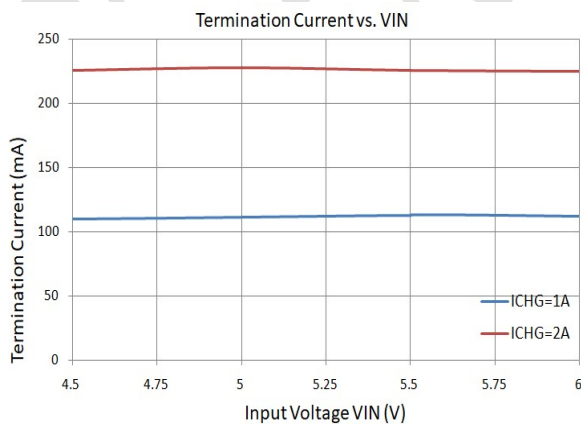


Figure 5. Termination Current vs. Input Voltage

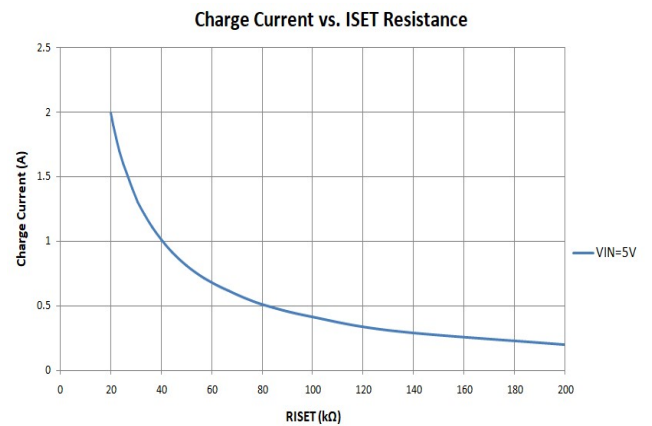
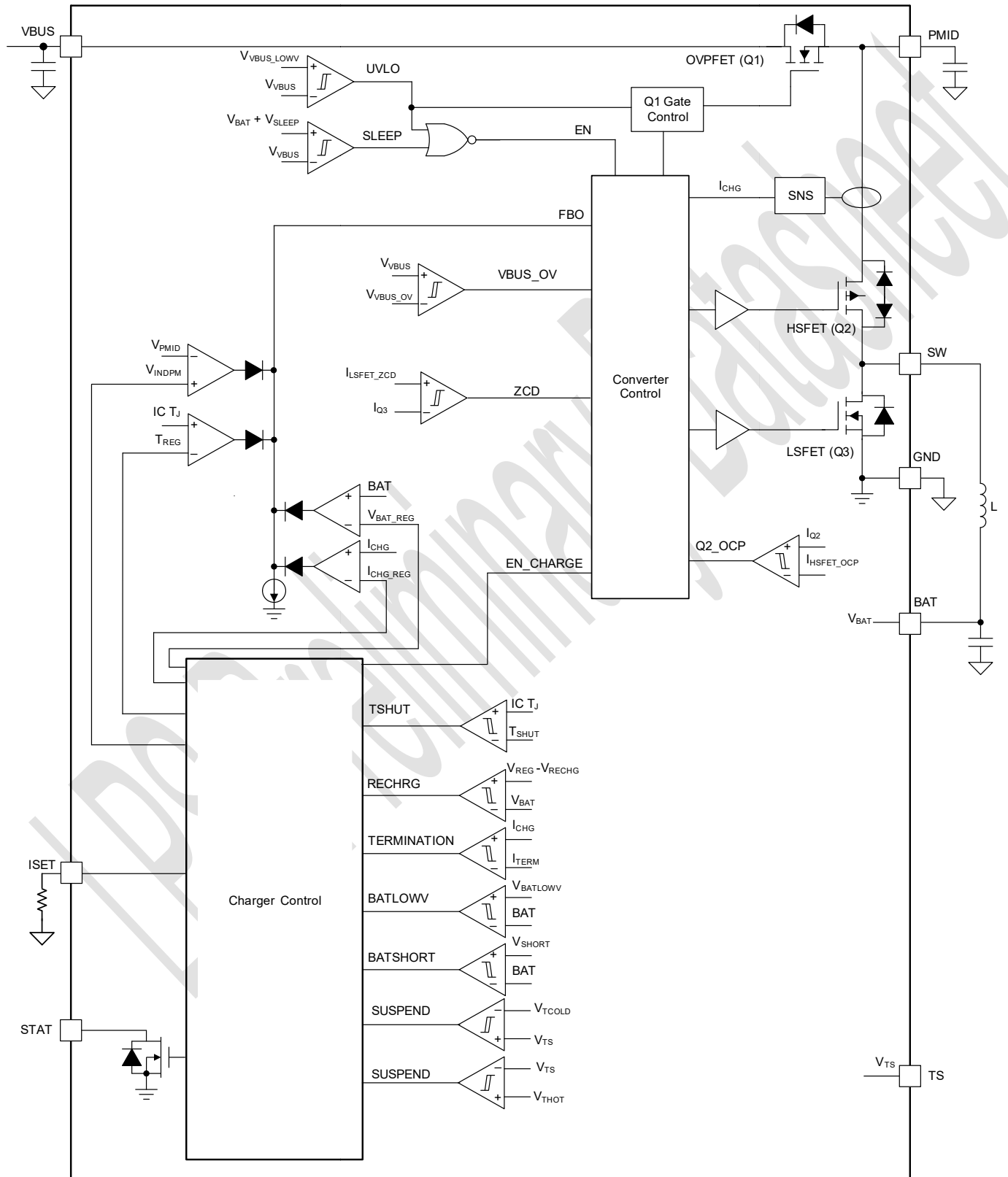


Figure 6. Charge Current vs. R_{ISET}

Functional Block Diagram



Detailed Description

Input Over Voltage Protection (OVP)

The LP4022H comprises of input over voltage protection followed by a Buck charger. During power-up from VBUS, OVPFET soft-start after V_{VBUS} reaches UVLO threshold V_{UVLO_RISE} for a delay time. Following the OVPFET soft-start, charger is enabled if charge mode condition is met. If the input voltage V_{VBUS} exceeds the OVP threshold, the P-channel OVPFET gate voltage is pulled to a reference voltage such that PMID voltage is clamped at V_{PMID_CLAMP} . Buck charger is connected between PMID and a battery.

Charger Power-up

If ISET pin is not shorted, internal LDO successful power-up, if there is no faults detected, the device powers up and charge is enabled. The faults include:

- Input OVP fault: $V_{VBUS} > V_{VBUS_OVP}$
- TS cold/hot fault
- Junction temperature is above T_{SHUT}

Device Functional Mode

The device operates in different modes depending on VBUS voltage, battery voltage and ISET pin connection. The functional modes are listed in the following table.

Table 1: Device Functional Mode

MODE	CONDITIONS	CHARGE	STAT
ISET Pin High	ISET pin open or pulled higher than 1V	NO	PULLED LOW
ISET Pin Short	ISET pin is shorted to GND	NO	OPEN
HiZ Mode	$V_{VBUS} < V_{UVLO}$	NO	OPEN
Sleep Mode	$V_{VBUS} > V_{UVLO}$ $V_{VBUS} < V_{BAT} + V_{SLEEP_Z}$	NO	OPEN
Charge Mode	$V_{VBUS} > V_{UVLO}$ $V_{VBUS} > V_{BAT} + V_{SLEEP_Z}$ $V_{VBUS} < V_{VBUS_OVP_RISE}$	YES	PULLED LOW
Charge Termination Mode	$V_{VBUS} > V_{UVLO}$ $V_{VBUS} > V_{BAT} + V_{SLEEP_Z}$ $V_{VBUS} < V_{VBUS_OVP}$ No faults and charge is terminated	NO	OPEN
Fault Mode	<ul style="list-style-type: none"> • Input OVP • TS Cold/Hot • Thermal Shutdown 	NO	OPEN

Battery Charge Profile

In Charge Mode as shown in the table of Device Functional Mode, the devices charge the battery in four sub-charge-modes: trickle charge, pre-charge, Constant Current (CC) charge and Constant Voltage (CV) charge as shown in Figure 7. If the battery voltage falls below $V_{BAT_SHORT_FALL}$, the battery charge battery with trickle charge current I_{BAT_SHORT} , when the battery voltage rises above $V_{BAT_SHORT_RISE}$ and below $V_{BAT_LOWV_RISE}$, the charger charges battery in precharge mode with charge current at I_{PRECHG} . Fast charge starts once battery voltage rises above $V_{BAT_LOWV_RISE}$. When battery voltage is close to battery charge voltage V_{BATREG} , the charger goes into CV mode and charge current starts to decrease. When charge current decreases below termination current I_{TERM} , charge is terminated and charge cycle ends. Following charge termination, if the battery voltage follows below $(V_{BATREG} - V_{RECHG_HYS})$, a new charge cycle restarts.

Trickle Charge

Under battery short condition, the device charges the battery at a fixed charge current I_{BAT_SHORT} if the battery is below $V_{BAT} < V_{BAT_SHORT}$. VINDPM and thermal regulation is enabled during trickle charge.

Precharge

The device charges the battery at 10% of programmed fast charge current I_{CHG} in precharge mode. Precharge is enabled in charge mode when the precharge condition $V_{BAT_SHORT_RISE} < V_{BAT} < V_{BAT_LOWV_RISE}$ is met.

Constant Current (CC) Charge

CC charge is also called fast charge. The device charges the battery from Buck converter at current level of $K_{I_{CHG}} / R_{ISET}$, where $K_{I_{CHG}}$ is the gain of charge current setting.

Constant Voltage (CV) Charge

With the battery voltage charged up, the BAT pin voltage reaches the battery regulation voltage V_{BATREG} and the charge current starts to decrease from fast charge current I_{CHG} . The actual battery voltage keeps increasing until charge termination is triggered.

Charge Termination

The device terminates a charge cycle when the battery voltage is above recharge threshold $(V_{BATREG} - V_{RECHG_HYS})$ and the charge current is below termination current I_{TERM} for deglitch time t_{TERM} . The termination current threshold I_{TERM} is 10% of fast charge current I_{CHG} , which is set by the R_{ISET} resistor connected at ISET pin.

Battery Recharge

Once a charge cycle is terminated, if battery voltage V_{BAT} decreases below the recharge threshold $(V_{BATREG} - V_{RECHG_HYS})$ and the charge mode conditions are met, the charger is enabled again. In addition to recharge, charge cycle starts if V_{VBUS} voltage is recycled or fault conditions are cleared or ISET pin is released from a short condition even with the battery voltage above the recharge threshold.

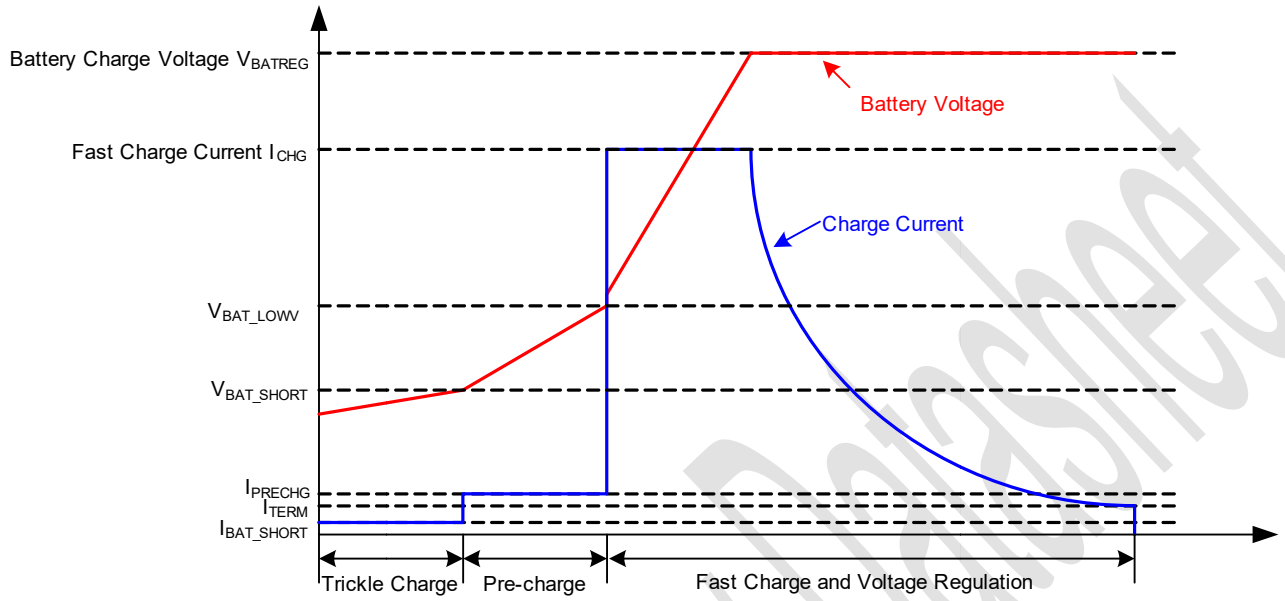


Figure 7. Battery Charge Profile

Table 2. Charge Current in Charge Mode

CHARGE MODE	BATTERY VOLAGE V_{BAT}	CHARGE CURRENT	TYPICAL VALUES
Trickle Charge	$V_{BAT} < V_{BAT_SHORT_FALL}$	I_{BAT_SHORT}	60mA
Precharge	$V_{BAT_SHORT_RISE} < V_{BAT} < V_{BAT_LOWV}$	I_{PRECHG}	10% of I_{CHG}
Fast Charge	$V_{BAT_LOWV} < V_{BAT} < V_{BATREG}$	I_{CHG}	K_{ICHG} / R_{ISET}
CV Charge	$V_{BAT_LOWV} < V_{BAT} < V_{BATREG}$	$< I_{CHG}$	Variable

Battery Temperature Monitoring

The charger device provides a single NTC thermistor input TS pin for battery temperature monitor. RT1 and RT2 resistor programs the cold temperature T1 and hot temperature T3. In the Equations (1) and (2), RNTC,T1 is NTC thermistor resistance value at temperature T1 and RNTC,T3 is NTC thermistor resistance values at temperature T3. VT1% and VT3% can be found in the Electronic Characteristics table. Select 0°C to 45°C for battery charge temperature range, then NTC thermistor 103AT-2 resistance are RNTC,T1 = 27.28 kΩ (at 0°C) and RNTC,T3 = 4.91 kΩ (at 45°C). From Equation (1) and Equation (2), RT1 and RT2 are derived as below, which is the resistance to set the charge temperature range 0 to 45°C.

- RT1 = 4.52 kΩ
- RT2 = 23.2 kΩ

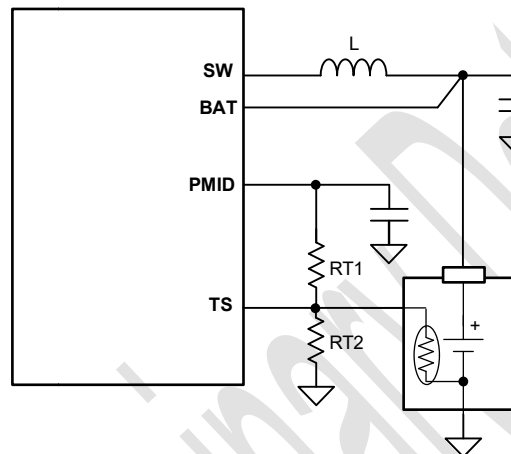


Figure 8. Battery Temperature Monitoring

$$RT2 = \frac{R_{NTC,T1} \times R_{NTC,T3} \times \left(\frac{1}{V_{T3\%}} - \frac{1}{V_{T1\%}} \right)}{R_{NTC,T1} \times \left(\frac{1}{V_{T1\%}} - 1 \right) - R_{NTC,T3} \times \left(\frac{1}{V_{T3\%}} - 1 \right)} \quad (1)$$

$$RT1 = \frac{\frac{1}{V_{T1\%}} - 1}{\frac{1}{RT2} + \frac{1}{R_{NTC,T1}}} \quad (2)$$

If TS is open, TS function is disabled. If TS function is not used, just leave TS pin open.

Fault Mode

Any fault below triggers the charger into fault mode:

- Input OVP
- TS Cold/Hot
- Thermal Shutdown

In fault mode, the device stops charging. Once a fault is cleared, the charger goes back to charge mode if charge conditions are met.

ISET Pin

If ISET pin is open or pulled above higher than 1V, the charge current is near zero. If the ISET pin is pulled below 0.35V, the charge is disabled and STAT pin is open. ISET pin can be used as enable/disable input for charge current by pulling up or down ISET pin.

Input Voltage Dynamic Power Management (VINDPM)

When the input current of the device exceeds the current capability of the power supply, the charger device regulates VBUS voltage by reducing charge current to avoid crashing the input power supply. To charge a battery, the input voltage must be higher than actual V_{INDPM} threshold. In VINDPM regulation, termination is temporarily disabled.

Maximum Duty Cycle D_{max} and 100% Duty Cycle

The Buck converter implemented HSFET maximum duty cycle and 100% duty cycle. When a weak input source (due to long input cable or lower power level of an adaptor) is connected at VBUS, the HSFET duty cycle increases. If D_{max} is reached and the closed-loop regulation still cannot regulate current or voltage, then HSFET turns on with 100% duty cycle. By implementing 100% duty cycle, the Buck converter operates in pass-through mode and charge current is maximized and efficiency jumps to higher level.

Thermal Regulation (TREG)

The device monitors the junction temperature T_J to avoid overheating the chip and limit the device surface temperature. When the internal junction temperature exceeds thermal regulation limit T_{REG} , the device lowers down the charge current. During thermal regulation, the average charging current is reduced below the programmed battery charging current. In thermal regulation, termination is temporarily disabled.

Thermal Shutdown (TSHUT)

The devices have thermal shutdown built in to turn off the charger when device junction temperature exceeds T_{SHUT} . The charger is re-enabled when the junction temperature is 25°C below T_{SHUT} . During thermal shutdown, charge is suspended and the charger goes into fault mode.

Application and Implementation

Application Information

The device can be used for general purpose high efficiency fast charger. The charge current is programmable by a resistor from ISET pin to GND. The charge can be enabled or disabled by a MCU GPIO connected to ISET pin or TS pin as shown in Figure 9 and Figure 10.

Application Schematic

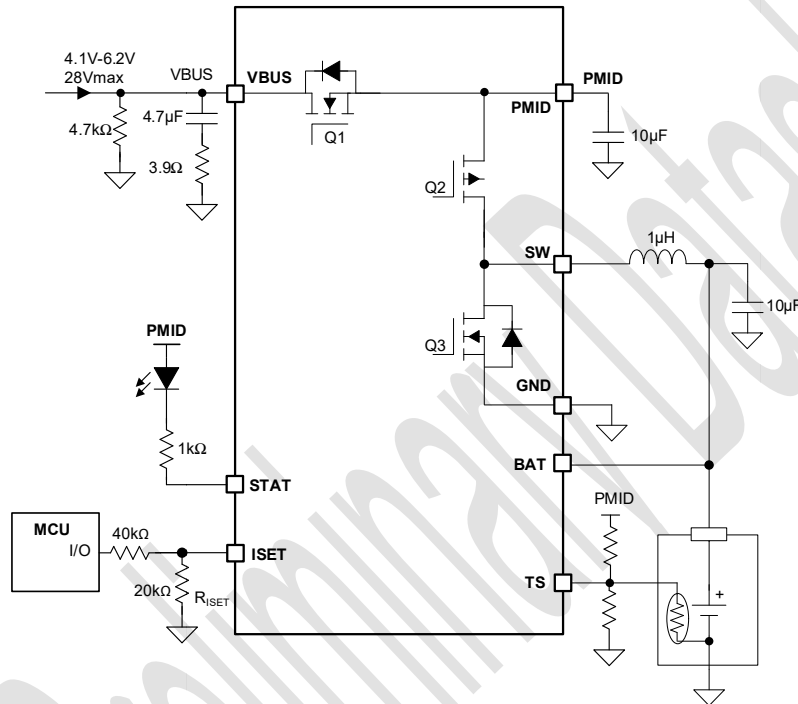


Figure 9: Typical Applications Schematic (MCU enable/disable charge with ISET pin pulled high)

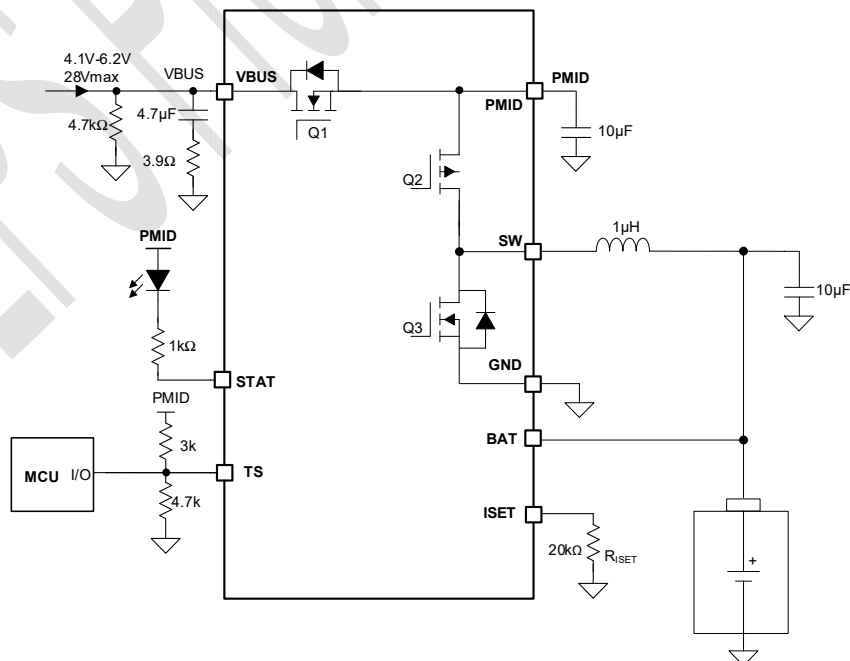


Figure 10: Typical Applications Schematic (MCU enable/disable charge with TS pin pulled low)



Charge Current Setting

The charger current is set by the resistor value at the ISET pin according to the equation below:

$$I_{\text{CHG}} (\text{A}) = K_{\text{ICHG}} (\text{A} \cdot \text{k}\Omega) / R_{\text{ISET}} (\text{k}\Omega) \quad (3)$$

K_{ICHG} is current setting gain that is listed in Electrical Characteristics table and R_{ISET} is the resistor value from ISET pin to GND. K_{ICHG} is typically 40 (A·kΩ).

Input Hot Plug-In

To attenuate potential input voltage spike caused by cable parasitic inductance during adaptor hot plug-in, there is a 3.9Ω resistor in series with the 4.7μF input capacitor. 4.7kΩ is used to discharge the input capacitor in case there is contact bounce.

Application Curves

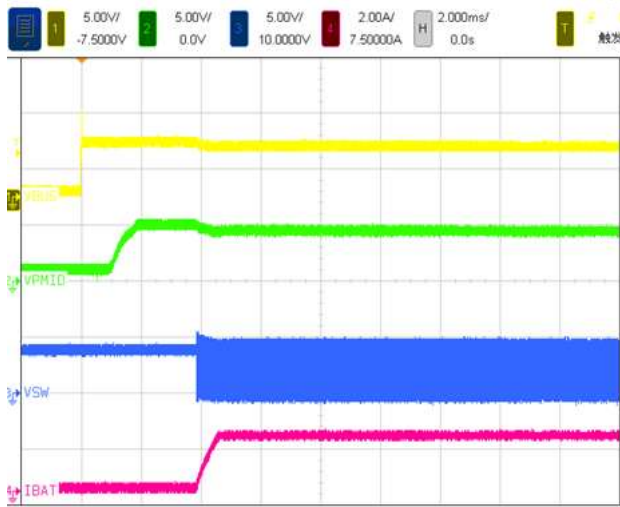


Figure 11. Power-up from VBUS
($V_{VBUS}=5V$, $V_{BAT}=3.8V$, $I_{CHG}=2A$)

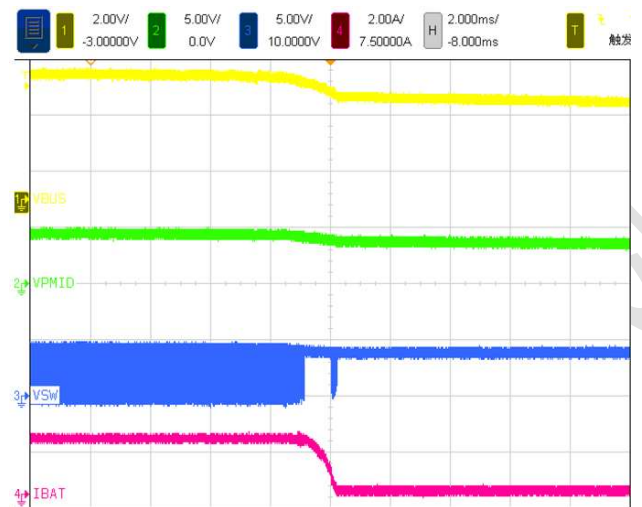


Figure 12. Power-down from VBUS
($V_{VBUS}=5V$, $V_{BAT}=3.8V$, $I_{CHG}=2A$)

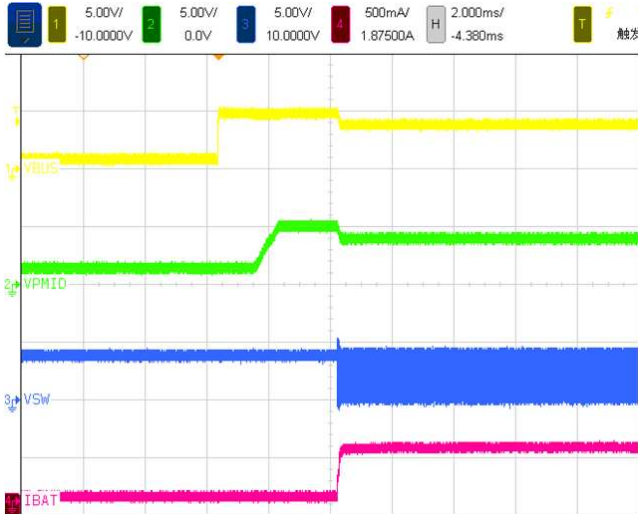


Figure 13. Power-up into VINDPM
($V_{VBUS}=5V$, $V_{BAT}=3.8V$, $I_{CHG}=2A$)

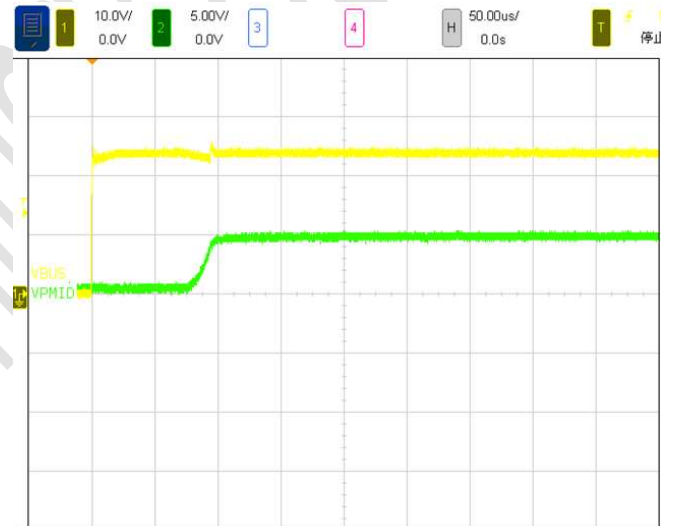


Figure 14. VBUS hot plug-in
($V_{VBUS}=24V$, $V_{BAT}=3.8V$, $I_{CHG}=2A$)

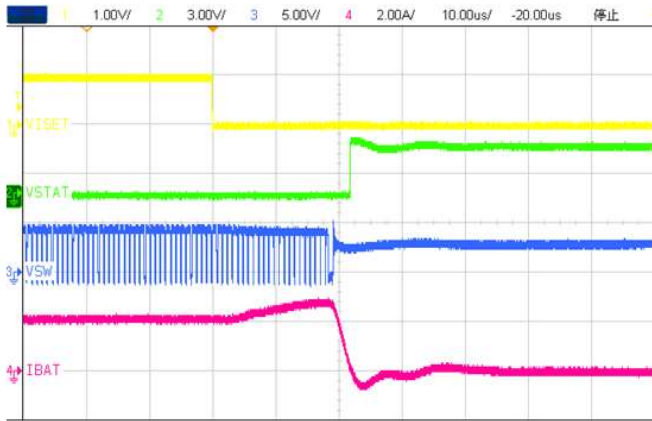


Figure 15. ISET Short
($V_{VBUS}=5V$, $V_{BAT}=3.8V$, $I_{CHG}=2A$)

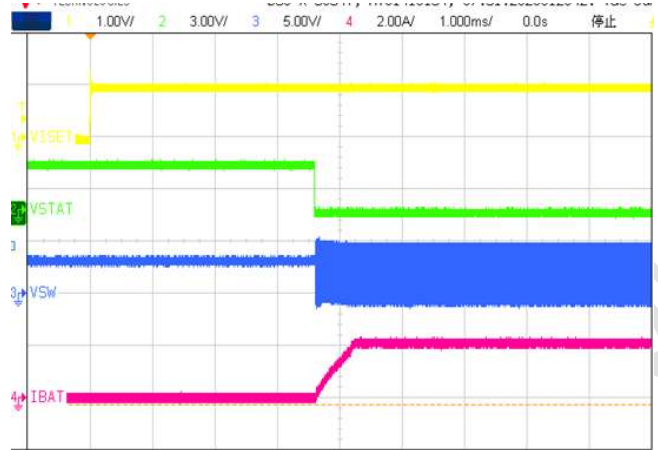


Figure 16. ISET Released from Short
($V_{VBUS}=5V$, $V_{BAT}=3.8V$, $I_{CHG}=2A$)

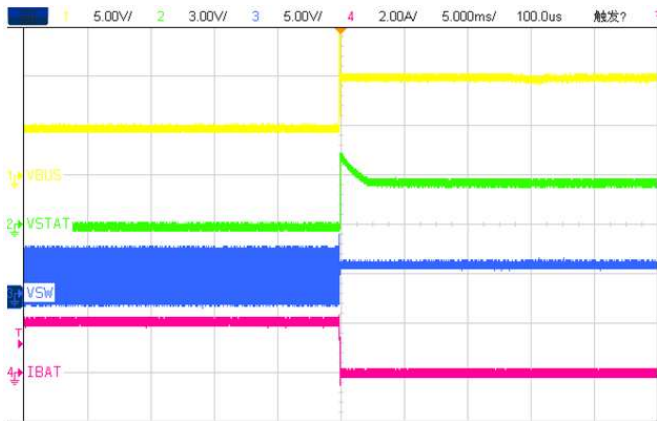


Figure 17. Input Over Voltage
($V_{VBUS}=5V$ to $15V$, $V_{BAT}=3.8V$, $I_{CHG}=2A$)

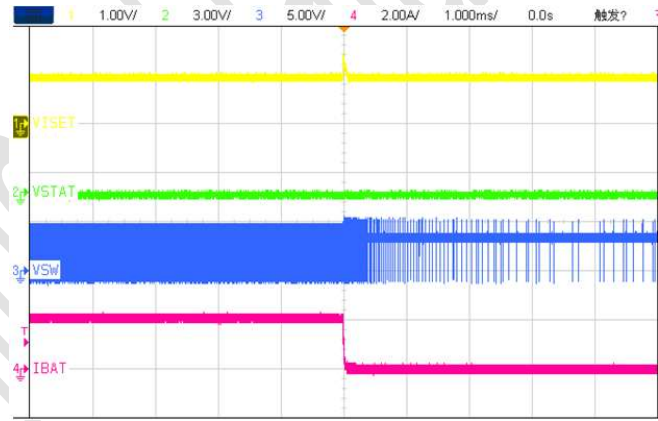
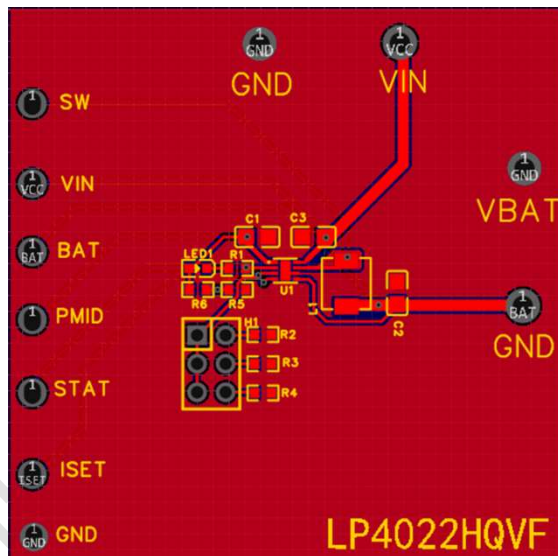


Figure 18. RISET Floating or Pulled High
($V_{VBUS}=5V$, $V_{BAT}=3.8V$, $I_{CHG}=2A$)

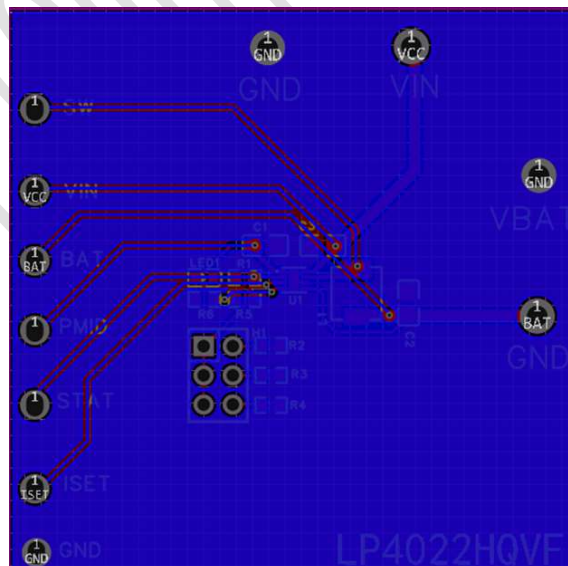
PCB Layout Guideline

Appropriate PCB layout is important in the power supply design. Good PCB layout minimizes EMI and noises, allows good output voltage regulation and achieves higher efficiency. The following design considerations are recommended:

- Decouple PMID and VBUS pins to power GND on top layer and place decoupling capacitors as close to those pins as possible. Always avoid vias if possible because they have parasitic inductance and resistance. If vias are inevitable, always use more than one vias in parallel to decrease parasitics for power traces.
- Connect IC GND pad to the power ground plane on the bottom side with multiple vias that is for both heat dissipation and electrical connection.
- Minimize switching SW node size and trace lengths and keep it away from ISET and BAT traces.
- A PCB layout example is shown in Figure 19.



Top Layer



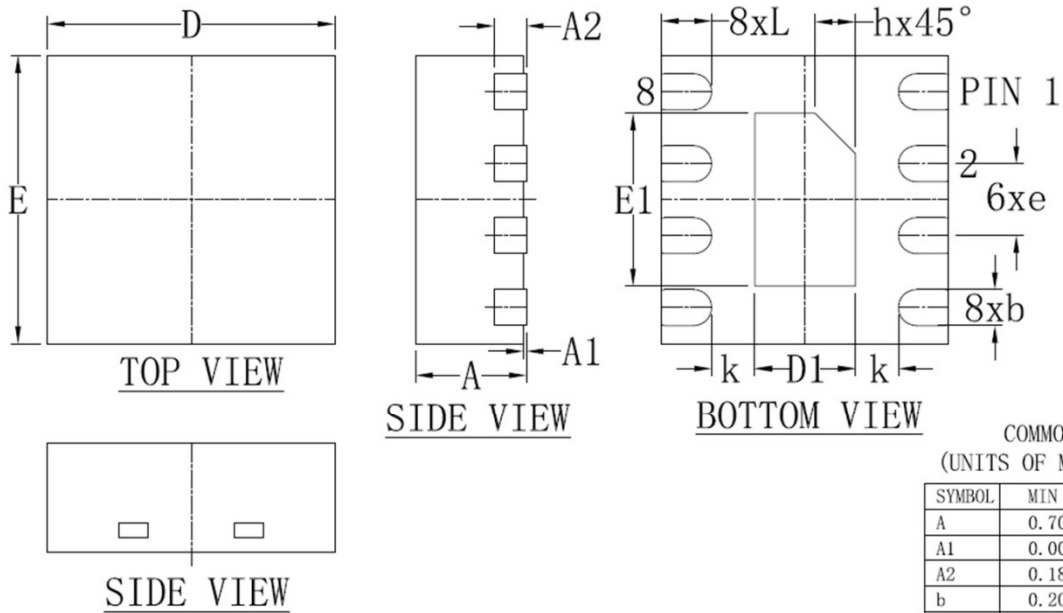
Bottom Layer

Figure 19. 2-layer PCB Layout Example



Packaging Information

DFN2x2-8

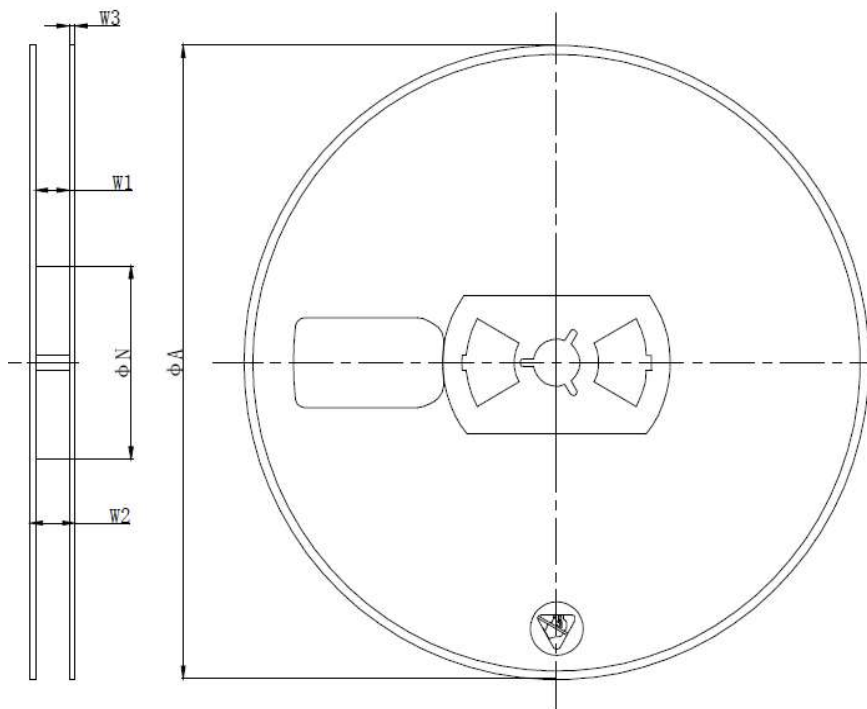


COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	0.700	0.750	0.800
A1	0.000	/	0.050
A2	0.180	0.203	0.220
b	0.200	0.250	0.300
D	1.900	2.000	2.100
D1	0.600	0.700	0.800
E	1.900	2.000	2.100
E1	1.100	1.200	1.300
e	0.475	0.500	0.525
h	0.230	0.280	0.330
k	0.280	0.300	0.320
L	0.300	0.350	0.400

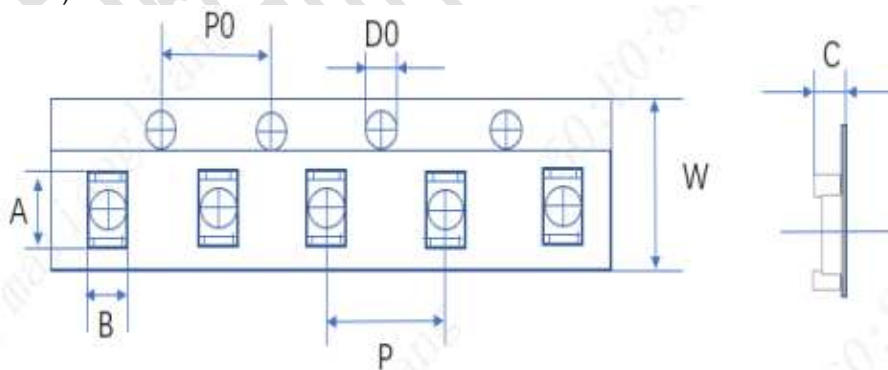
Carrier Information

Reel Dimensions (Unit: mm)



Device	ΦA	W2
LP4022HQVF	180±4	12±3

Tape Dimension (Unit: mm)



Device	A	B	P0	P	D0	W	C
LP4022HQVF	2.15±0.30	2.15±0.30	4.00±0.20	4.00±0.20	1.50±0.20	8.00±0.30	1.0±0.20

Pin 1 and Tape Feeding Direction

